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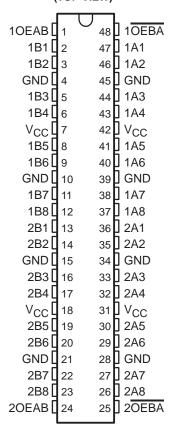
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OI</sub>)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

## description

The 'ABT16623 are 16-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT16623 provide true data at the outputs.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (32 total) remain at their last states.

#### SN54ABT16623 . . . WD PACKAGE SN74ABT16623 . . . DGG OR DL PACKAGE (TOP VIEW)





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SCBS211B - FEBRUARY 1991 - REVISED JANUARY 1997

# description (continued)

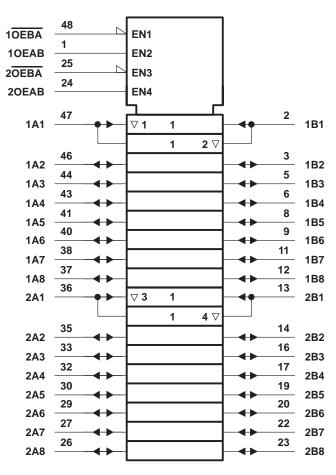
To ensure the high-impedance state during power up or power down,  $\overline{\text{OEBA}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16623 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16623 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 8-bit section)

INP	UTS						
OEBA	OEAB	OPERATION					
L	L	B data to A bus					
L	Н	B data to A bus, A data to B bus					
Н	L	Isolation					
Н	Н	A data to B bus					

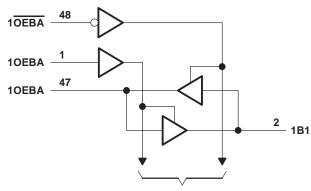
# logic symbol†

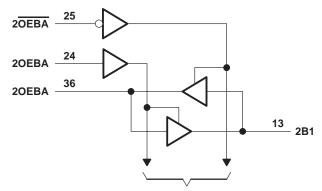


<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



# logic diagram (positive logic)





**To Seven Other Channels** 

To Seven Other Channels

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$\dots$ -0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	$\dots$ -0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16623	96 mA
SN74ABT16623	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T <sub>stq</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

# recommended operating conditions (see Note 3)

			SN54ABT	16623	SN74ABT	16623	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EM	2		V	
VIL	IL Low-level input voltage					0.8	V
VI	Input voltage		0 0	VCC	0	VCC	V
ІОН	High-level output current		Ç	-24		-32	mA
l <sub>OL</sub>	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	A)	5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

# SN54ABT16623, SN74ABT16623 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS211B - FEBRUARY 1991 - REVISED JANUARY 1997

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETER	TEST 601	IDITIONS	Т	A = 25°C	;	SN54AB1	Г16623	SN74AB1	16623	UNIT	
PAR	AWEIER	TEST CON	IDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/~		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
\/a:		V00 - 4 5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V	
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V	
V <sub>hys</sub>					100						mV	
l <sub>l</sub>	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	μΑ	
	A or B ports					±100		±100		±100	-	
lozh <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			50		50		50	μΑ	
lozL <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-50	4	<b>–</b> 50		-50	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100	2/			±100	μΑ	
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50	Ongc	50		50	μΑ	
IO§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	<del>2</del> –50	-180	-50	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high			2		2		2		
Icc	A or B ports	$I_{O} = 0$ ,	Outputs low			35		35		35	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
	Data innuta	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1		1.5		1		
∆ICC¶	Data inputs	Other inputs at V <sub>CC</sub> or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5		
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			8						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters IOZH and IOZL include the input leakage current.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

# SN54ABT16623, SN74ABT16623 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

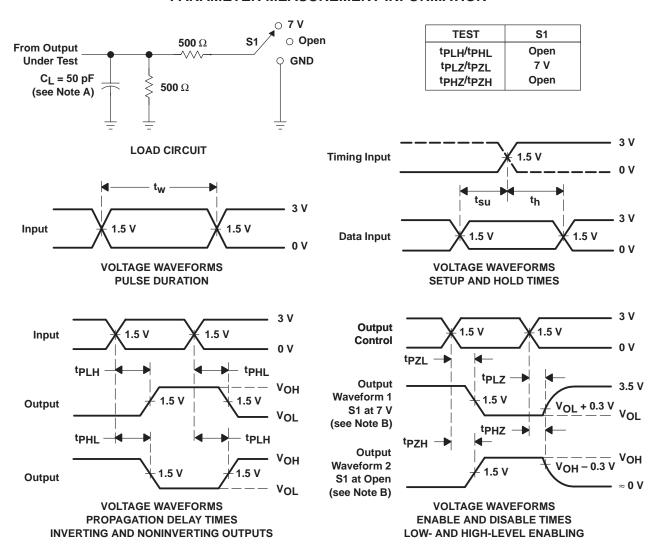
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# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO		FROM TO $V_{CC} = 5 \text{ V},$ $T_{A} = 25^{\circ}\text{C}$				Г16623	SN74AB	UNIT	
	(IIII O1)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	A or B	B or A	1	2	3.2	1	3.7	1	3.6	no
t <sub>PHL</sub>	AUID	D OI A	1	2.2	3.4	1 (	4.4	1	4.3	ns
<sup>t</sup> PZH	<u> </u>	A or B	1.1	3	4	1.1	5	1.1	4.9	no
tpZL	OEBA or OEAB	AUB	1.4	3.3	4.9	1.4	6.2	1.4	6	ns
t <sub>PHZ</sub>	OEBA or OEAB	A or B	1	3.5	4.9	0 1	6.2	1	6	ns
t <sub>PLZ</sub>	OEDA UI OEAB		1.4	2.8	4.7	1.4	5.6	1.4	5.4	

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ABT16623DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16623	Samples
SN74ABT16623DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16623	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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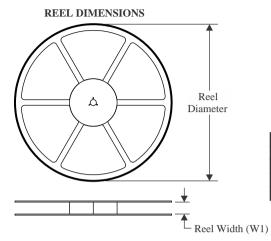
# **PACKAGE OPTION ADDENDUM**

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# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

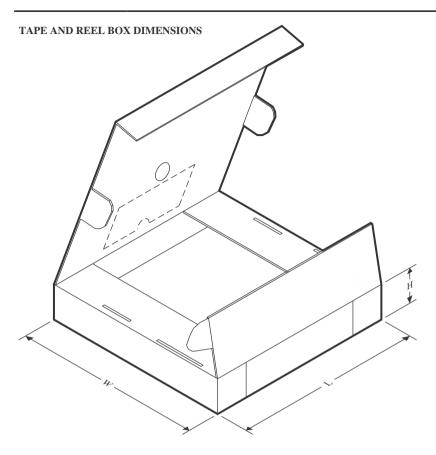


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16623DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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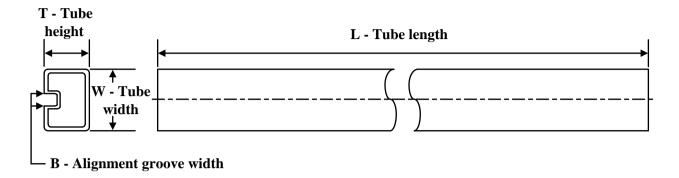
## \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74ABT16623DLR	SSOP	DL	48	1000	367.0	367.0	55.0

# **PACKAGE MATERIALS INFORMATION**

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# **TUBE**



## \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT16623DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

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